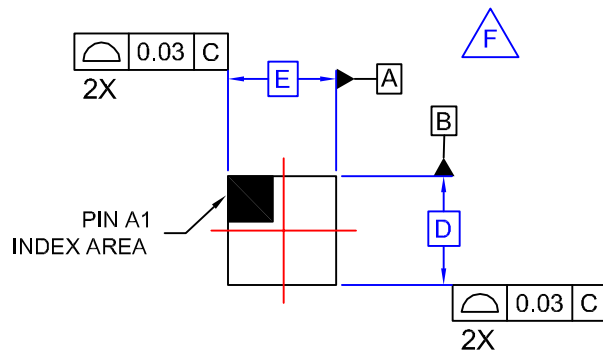
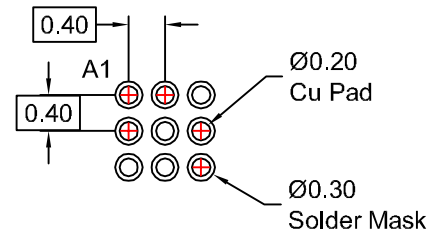


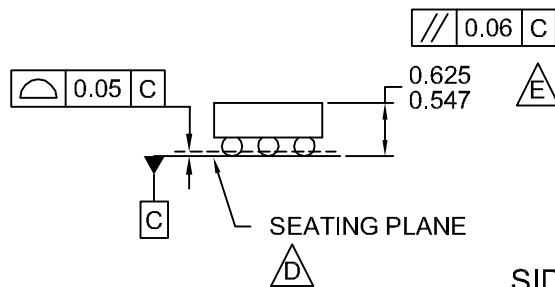
REVISIONS			
REV	DESCRIPTION	DATE	BY/SITE
1	INITIAL DRAWING RELEASE.	2-15-2008	L. ENGLAND/FSME
2	Updated land pattern to individual solder mask openings. Removed solder alloy note. Other misc updates for standardization.	4-9-2010	L. ENGLAND/FSME



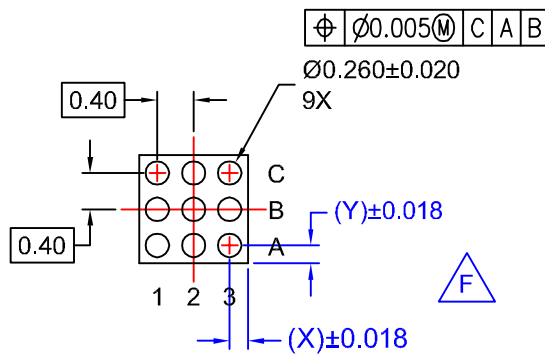
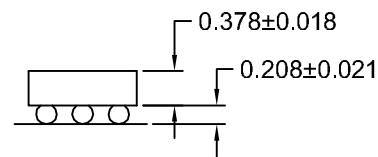
TOP VIEW



LAND PATTERN RECOMMENDATION
(NSMD PAD TYPE)



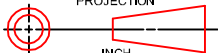
SIDE VIEWS



BOTTOM VIEW

NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASMEY14.5M, 1994.
- D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE NOMINAL HEIGHT IS 586 MICRONS ±39 MICRONS (547-625 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.
- G. DRAWING FILNAME: MKT-UC009ABrev2

APPROVALS		DATE	FAIRCHILD SEMICONDUCTOR™			
DRAWN	L. England	4-9-10	9 BALL WLCSP, 3X3 ARRAY 0.4MM PITCH, 250UM BALL			
DFTG. CHK.	H. Allen	4-9-10				
ENGR. CHK.						
 INCH [MM]			SCALE	SIZE	DRAWING NUMBER	REV
			N/A	N/A	MKT-UC009AB	2
DO NOT SCALE DRAWING					SHEET 1 of 1	